

Title (en)
CONDUCTIVE POLYMER DEVICE

Title (de)
BAUELEMENT AUS LEITENDEM POLYMER

Title (fr)
DISPOSITIF A POLYMERE CONDUCTEUR

Publication
EP 0490989 B1 19991124 (EN)

Application
EP 90914344 A 19900910

Priority
• US 9005102 W 19900910
• US 40473089 A 19890908

Abstract (en)
[origin: WO9103822A1] A melt-extrudable conductive polymer composition which contains a polymer, a particulate conductive filler and a particulate non conductive filler. When a standard strip heater is made from the composition and tested in a UL VW-1 test, it has comparable performance to a heater made from a second composition which is the same as the composition but which does not contain the non conductive filler. When tested in a standard arcing fault test, the standard heater will trip a fuse in less time than is required by the second heater, i.e. in less than 30 seconds. A preferred nonconductive filler is Sb2O3.

IPC 1-7
H01C 7/02

IPC 8 full level
H01B 1/20 (2006.01); **H01B 1/22** (2006.01); **H01B 1/24** (2006.01); **H01C 7/02** (2006.01); **H05B 3/14** (2006.01); **H05B 3/56** (2006.01)

CPC (source: EP KR)
H01B 1/20 (2013.01 - EP); **H01B 1/22** (2013.01 - EP); **H01B 1/24** (2013.01 - EP); **H01C 7/02** (2013.01 - KR); **H01C 7/027** (2013.01 - EP); **H05B 3/14** (2013.01 - EP); **H05B 3/146** (2013.01 - EP); **H05B 3/56** (2013.01 - EP)

Citation (examination)
US 4591700 A 19860527 - SOPORY UMESH K [US]

Cited by
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Designated contracting state (EPC)
AT BE CH DE DK ES FR GB IT LI NL SE

DOCDB simple family (publication)
WO 9103822 A1 19910321; AT E187013 T1 19991215; CA 2066254 A1 19910309; CA 2066254 C 19991102; DE 69033364 D1 19991230; DE 69033364 T2 20000727; EP 0490989 A1 19920624; EP 0490989 B1 19991124; JP H05500884 A 19930218; KR 920704316 A 19921219

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